Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit
Drain-Source Voltage		V_{DSS}	12	V
Gate-Source Voltage		V_{GSS}	±8	V
Continuous Drain Current, V_{GS} = 4.5V (Note 7)	T_C = +25°C	I_D	70	A
	T_C = +70°C		50	
Pulsed Drain Current (380µs Pulse, Duty Cycle = 1%)		I_{DM}	80	A
Maximum Continuous Body Diode Forward Current (Note 7)		I_S	70	A
Avalanche Current, L = 0.1mH (Note 8)		I_{AS}	34	A
Avalanche Energy, L = 0.1mH (Note 8)		E_{AS}	60	mJ

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit
Total Power Dissipation (Note 5)		P_D	0.9	W
Thermal Resistance, Junction to Ambient (Note 5)	Steady State	$R_{\theta JA}$	134	°C/W
Total Power Dissipation (Note 6)		P_D	1.9	W
Thermal Resistance, Junction to Ambient (Note 6)	Steady State	$R_{\theta JA}$	66	°C/W
Thermal Resistance, Junction to Case (Note 7)		$R_{\theta JC}$	3.4	
Operating and Storage Temperature Range		T_J, T_{STG}	-55 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 9)						
Drain-Source Breakdown Voltage	BV_{DSS}	12	—	—	V	V_{GS} = 0V, I_D = 250µA
Zero Gate Voltage Drain Current	I_{DSS}	—	—	1	µA	V_{DS} = 9.6V, V_{GS} = 0V
Gate-Source Leakage	I_{GSS}	—	—	±10	µA	V_{GS} = ±8V, V_{DS} = 0V
ON CHARACTERISTICS (Note 9)						
Gate Threshold Voltage	$V_{GS(TH)}$	0.3	—	1.0	V	V_{DS} = V_{GS}, I_D = 250µA
Static Drain-Source On-Resistance	$R_{DS(ON)}$	—	2.8	3.8	mΩ	V_{GS} = 4.5V, I_D = 15A
		—	3.2	5.1		V_{GS} = 2.5V, I_D = 10A
Diode Forward Voltage	V_{SD}	—	0.75	1.2	V	V_{GS} = 0V, I_S = 3.2A
DYNAMIC CHARACTERISTICS (Note 10)						
Input Capacitance	C_{iss}	—	2,385	—	pF	V_{DS} = 6V, V_{GS} = 0V, f = 1MHz
Output Capacitance	C_{oss}	—	678	—	pF	
Reverse Transfer Capacitance	C_{rss}	—	520	—	pF	
Gate Resistance	R_G	—	2.2	—	Ω	V_{DS} = 0V, V_{GS} = 0V, f = 1MHz
Total Gate Charge (V_{GS} = 4.5V)	Q_G	—	26	—	nC	V_{DS} = 6V, I_D = 10A
Total Gate Charge (V_{GS} = 8V)	Q_G	—	47	—	nC	
Gate-Source Charge	Q_{GS}	—	2.8	—	nC	
Gate-Drain Charge	Q_{GD}	—	5.3	—	nC	
Turn-On Delay Time	$t_{D(ON)}$	—	5.3	—	ns	V_{DD} = 6V, V_{GS} = 4.5V, R_G = 1Ω, I_D = 5A
Turn-On Rise Time	t_R	—	10.7	—	ns	
Turn-Off Delay Time	$t_{D(OFF)}$	—	31.6	—	ns	
Turn-Off Fall Time	t_F	—	16.9	—	ns	
Reverse Recovery Time	t_{RR}	—	24.3	—	ns	I_F = 2A, di/dt = 100A/µs
Reverse Recovery Charge	Q_{RR}	—	7.4	—	nC	

Notes:
5. Device mounted on FR-4 PC board, with minimum recommended pad layout, single sided.
6. Device mounted on FR-4 substrate PC board, 2oz copper, with thermal bias to bottom layer 1-inch square copper plate.
7. Thermal resistance from junction to soldering point (on the exposed drain pad).
8. I_{AS} and E_{AS} rating are based on low frequency and duty cycles to keep T_J = +25°C.
9. Short duration pulse test used to minimize self-heating effect.
10. Guaranteed by design. Not subject to product testing.

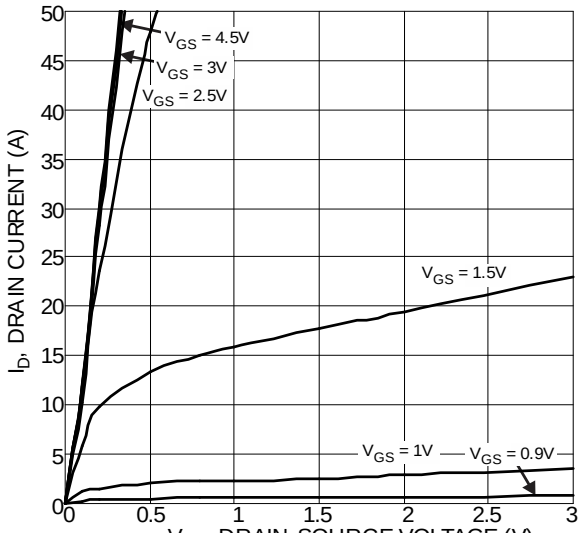


Figure 1 Typical Output Characteristic

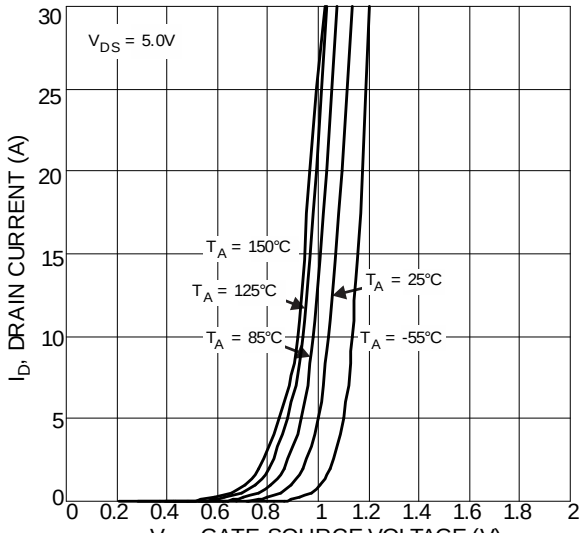


Figure 2 Typical Transfer Characteristics

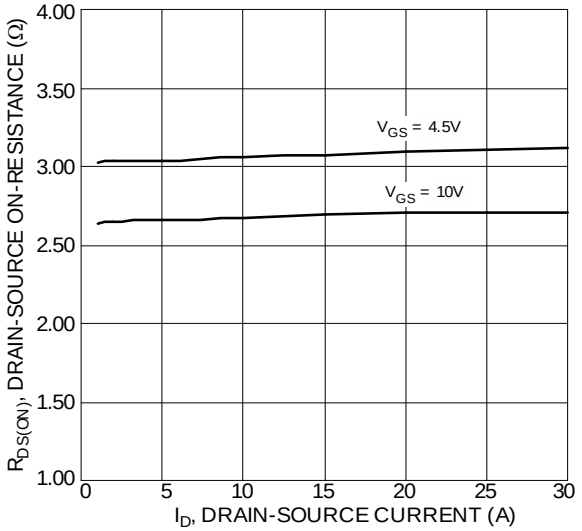


Figure 3 Typical On-Resistance vs. Drain Current and Gate Voltage

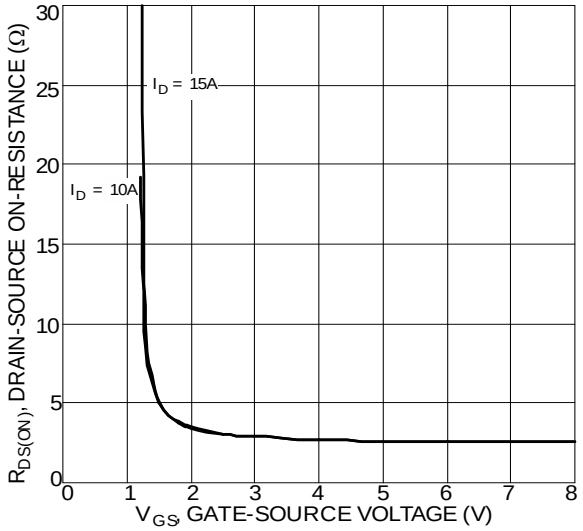


Figure 4 Typical Drain-Source On-Resistance vs. Gate-Source Voltage

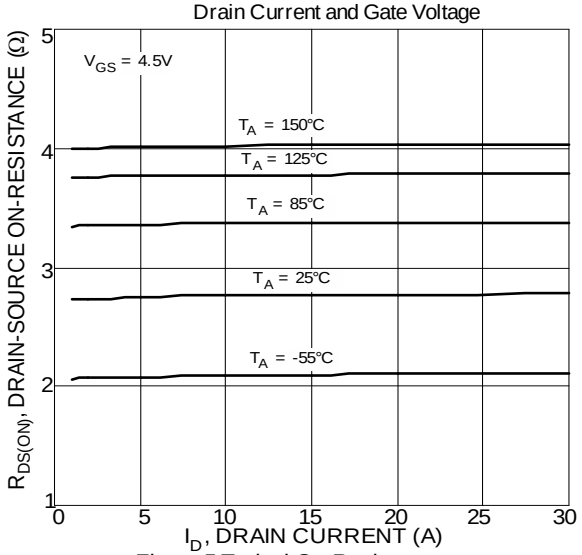


Figure 5 Typical On-Resistance vs. Drain Current and Temperature

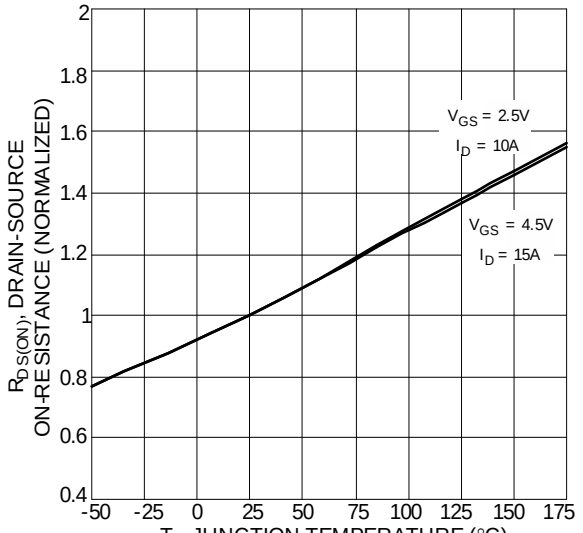


Figure 6 On-Resistance Variation with Temperature

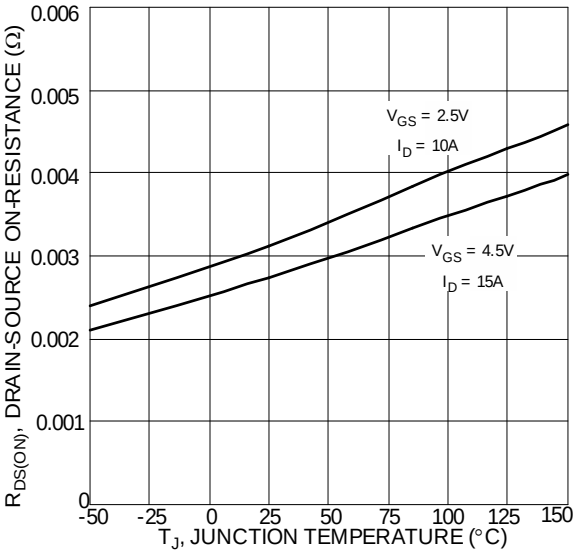


Figure 7 On-Resistance Variation with Temperature

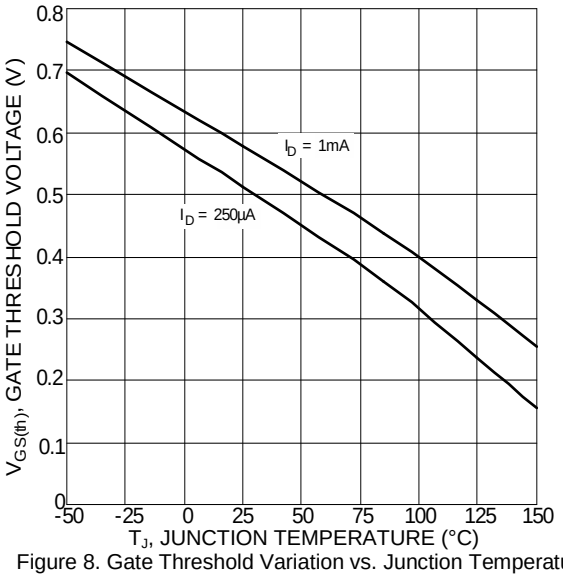


Figure 8. Gate Threshold Variation vs. Junction Temperature

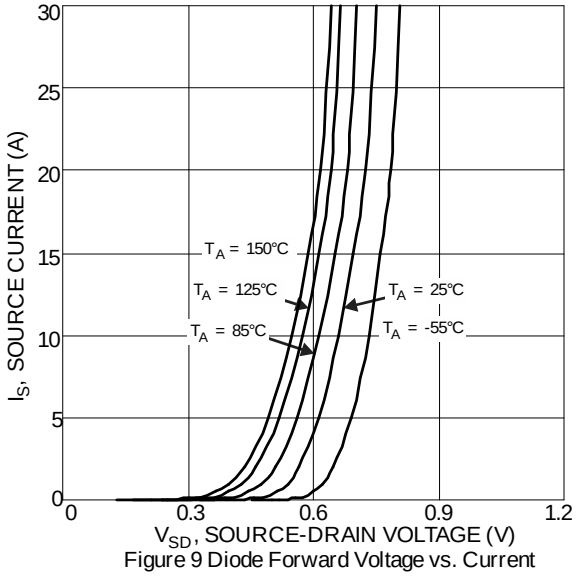


Figure 9 Diode Forward Voltage vs. Current

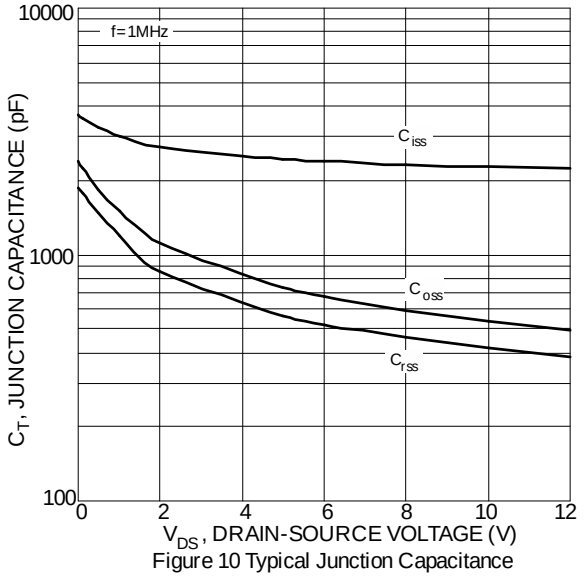


Figure 10 Typical Junction Capacitance

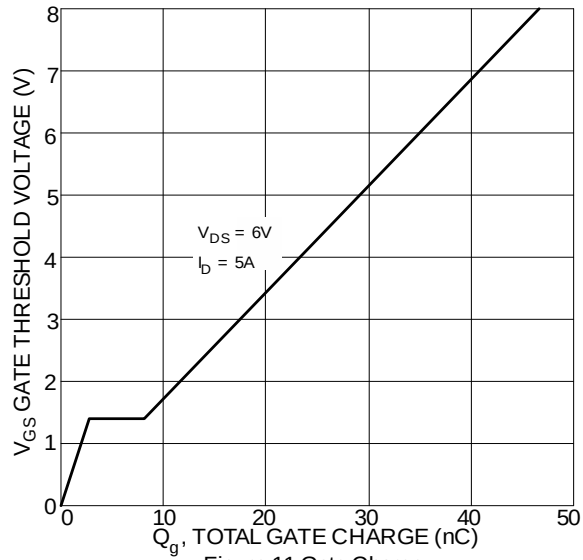


Figure 11 Gate Charge

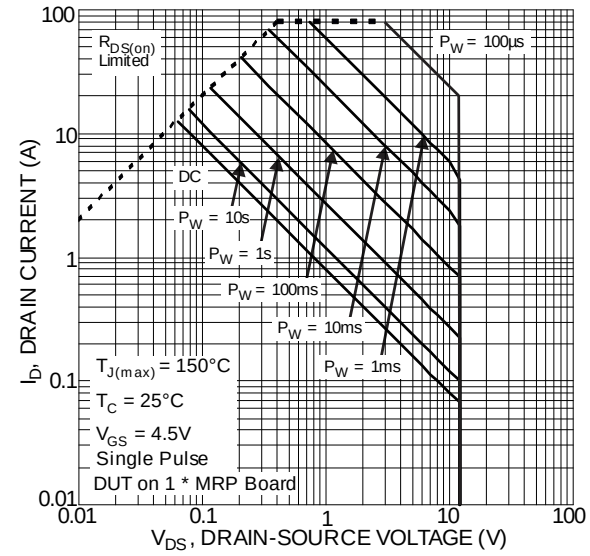


Figure 12 SOA, Safe Operation Area

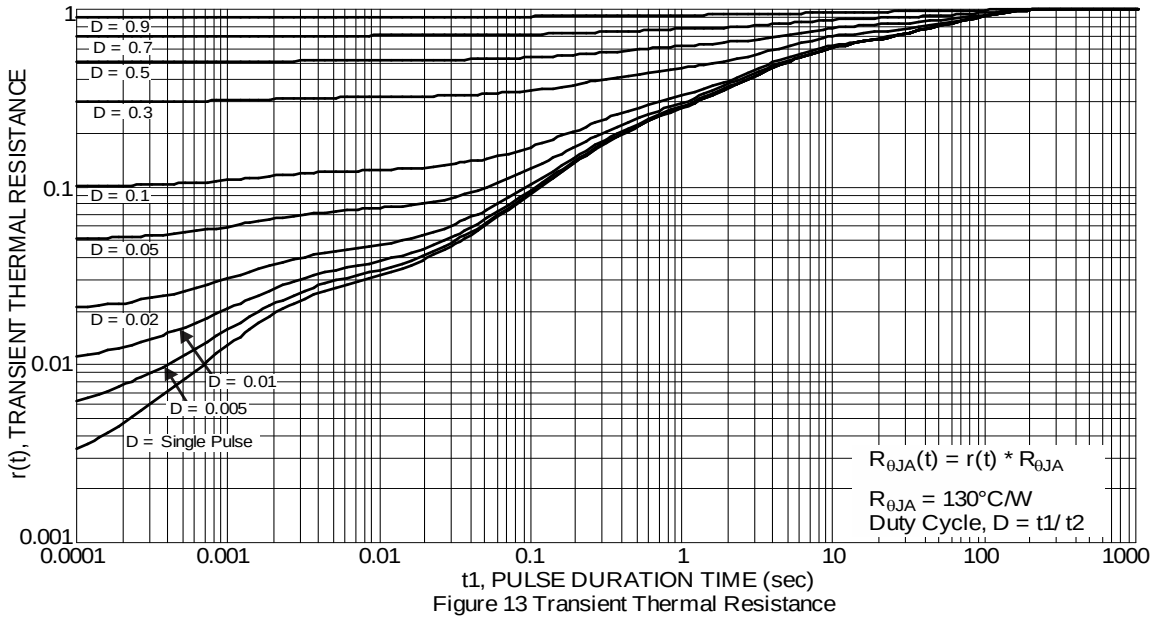
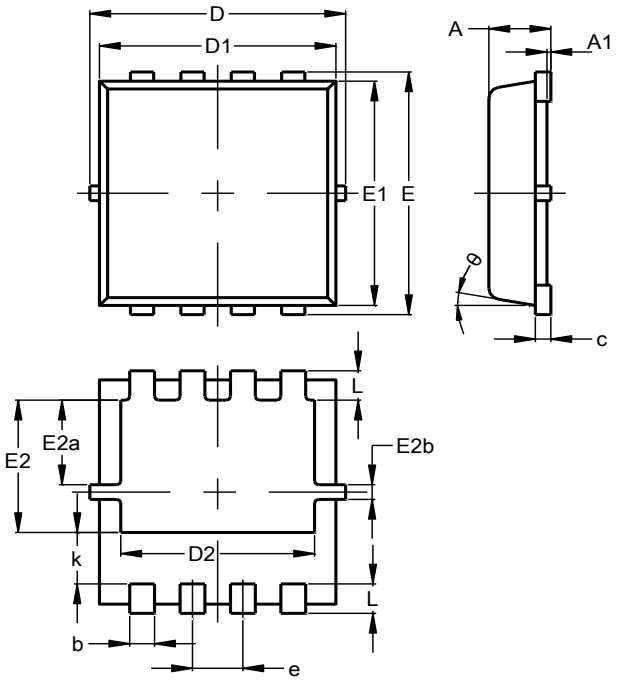


Figure 13 Transient Thermal Resistance

Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

PowerDI3333-8 (Type UX)

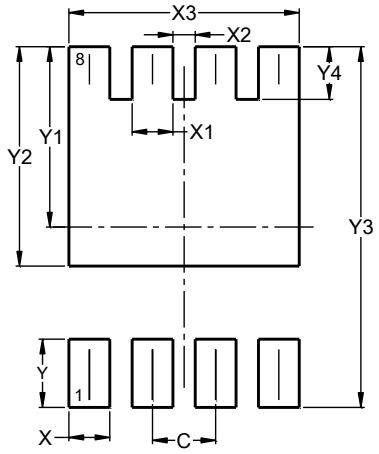


PowerDI3333-8 (Type UX)			
Dim	**Min**	**Max**	**Typ**
A	0.75	0.85	0.80
A1	0.00	0.05	--
b	0.25	0.40	0.32
c	0.10	0.25	0.15
D	3.20	3.40	3.30
D1	2.95	3.15	3.05
D2	2.30	2.70	2.50
E	3.20	3.40	3.30
E1	2.95	3.15	3.05
E2	1.60	2.00	1.80
E2a	0.95	1.35	1.15
E2b	0.10	0.30	0.20
e	0.65 BSC		
k	0.50	0.90	0.70
L	0.30	0.50	0.40
θ	0°	12°	10°
All Dimensions in mm			

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

PowerDI3333-8 (Type UX)



Dimensions	Value (in mm)
C	0.650
X	0.420
X1	0.420
X2	0.230
X3	2.370
Y	0.700
Y1	1.850
Y2	2.250
Y3	3.700
Y4	0.540

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